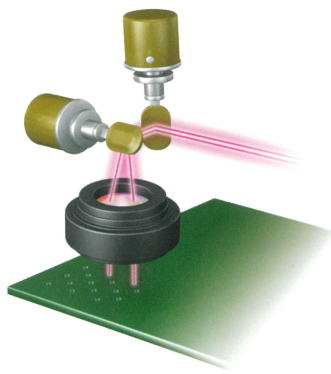


## 4-beam-2-panel model GTF5 series

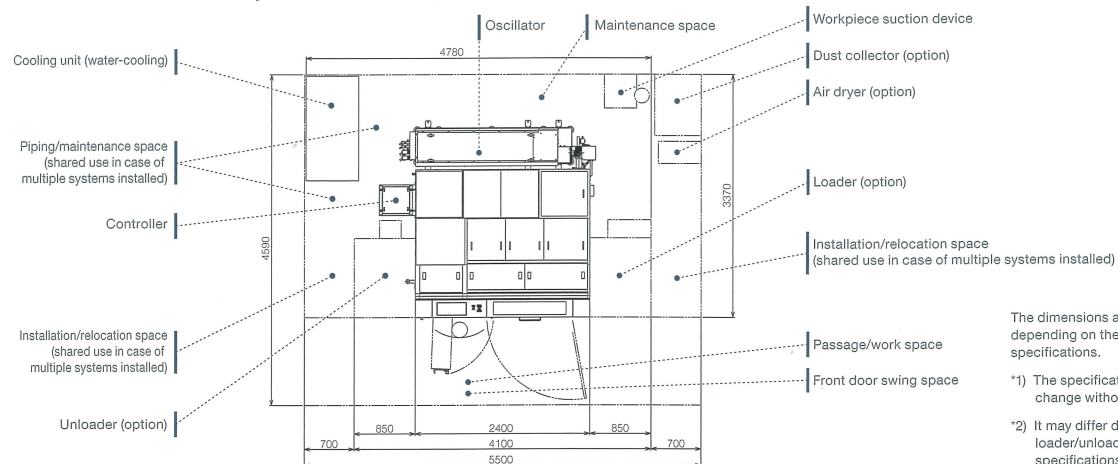
**CO<sub>2</sub>Laser**



### Specifications

Items			Specifications *1)
Systems	Model		ML605GTF5-5500UM
	Dimensions [mm]	Processing machine + Oscillator + Controller + Cooling unit + Workpiece suction device + Loader/unloader (option) *The height of the signal tower is included.	4780W×3370D×2270H *2)
	System weight [kg]		9000 *2)
Processing machine	X-Y table	Applicable workpiece size [mm]	610×510, 510×510 *Equipped with work clamps
		Maximum feed rate [m/min]	50
Oscillator	Laser type		CO <sub>2</sub> laser
	Power [W]		210
	Set frequency [Hz]		10 ~ 10000

### ML605GTF5-5500UM Layout



The dimensions and layout may differ depending on the option specifications.

\*1) The specifications are subject to change without notice.

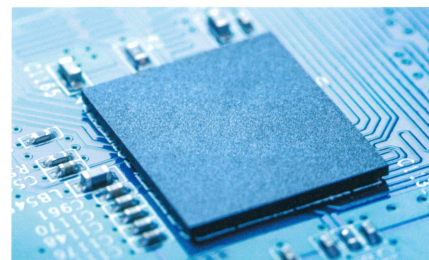
\*2) It may differ depending on the loader/unloader (option) specifications.

## High performance machine with high-speed, high-accuracy

### Specialized for resin substrates

Our 4-beam laser drilling machine, specialized for resin substrates, achieves consistent quality, high productivity and high positioning accuracy.

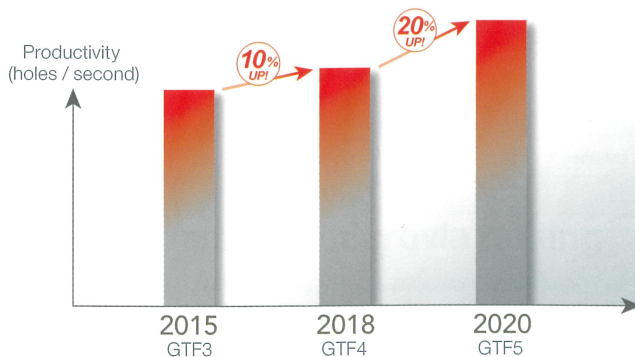
Major application:



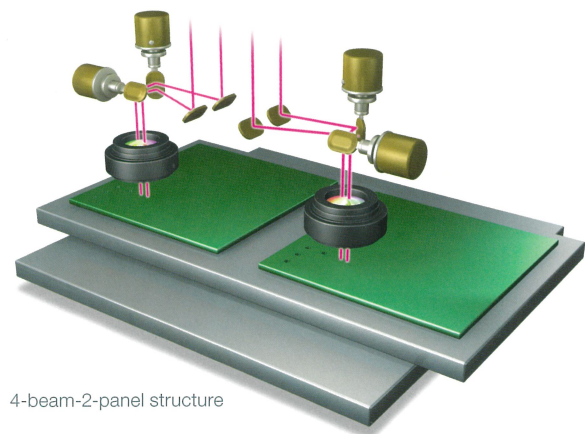
Package substrate

### Overwhelming productivity

Mitsubishi Electric's original 4-beam simultaneous processing optical system, laser oscillator for package substrate processing" ML5500UM "and high-speed galvano scanner "3200GL" achieve industry's top-class productivity.



\* The productivity varies depending on contents of the processing.



4-beam-2-panel structure

### Adapted for visualization and automation of laser processing.

Comforms to OPC, an international interoperability standard for the exchange of data in the industrial automation.

Provides an interface between individual production management system and SCADA system.

Pulse energy monitor function installed as default, monitoring the pulse energy per processing hole.

Realizes improved traceability.

